Achuta Kadambi

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Research

Sensing for AI, Computational Imaging, Digital Health, Sustainable Sensing

Education

PhD	MIT	2018
Visiting PhD student	Technion - Israel Inst. of Technology	2016
MS	Yale	2012
BS	Berkeley	2011

Academic Appointments

Assistant Professor UCLA Computer Science 2021-present
Assistant Professor UCLA Electrical / Computer Engineering 2018-present

Companies Founded

Co-founder Vayu Robotics 2022-Co-founder Akasha (acquired by Intrinsic/Alphabet) 2018-22

Awards

- 2022 **IEEE-HKN Outstanding Young Professional Award** (1 award/yr, under 35 yrs/age)
- 2021 NSF CAREER Award
- 2021 DARPA Young Faculty Award
- 2021 Army Research Office Young Investigator Award (ARO YIP)
- 2021 National Academy of Engineering (NAE) Frontiers of Engineering
- 2020 Google Faculty Award
- 2020 Senior Member National Academy of Inventors
- 2019 Forbes 30 under 30, Science
- 2019 NSF CRII Research Initiation Award
- 2019 Sony Imaging Young Faculty Award
- 2018 Best Paper Award, ICCP
- 2016 Lemelson-MIT Student Prize
- 2016 Rahamimoff Award, US-Israel Science Foundation
- 2016 Best Papers Special Issue Selection, ICCV
- 2016 Best Presentation Award, CVPR VIEW
- 2015 World Changing Idea, Scientific American
- 2014 Qualcomm Innovation Fellowship
- 2013 Draper Fellowship
- 2011 Regent and Chancellor Scholar, UC Berkeley

Awards won by Students

- 2022 NSF Graduate Research Fellowship GRFP (E. Zhao)
- 2021 Cisco PhD Fellowship (P. Chari)
- 2020 Guru Krupa Graduate Fellowship, UCLA (C. Talegaonkar)
- 2019 Best Undergraduate Demo, Annual Research Review (A. Padhye et al.)
- 2019 Best Poster Award, runner up, SoCal Machine Learning Day (Y. Ba et al)

Visiting Positions

2017 Visiting Researcher, Harvard Medical School, Boston MA (host: Prof. Rajiv Gupta)

- 2016 Visiting PhD Student, Technion, Israel (host: Prof. Yoav Y. Schechner)
- 2015 Intern, Microsoft Research, Redmond WA
- 2014 Intern, Mitsubishi Electric Research Labs (MERL), Cambridge MA

Invited Talks

- 2022 **Keynote**, CVPR UG2 Workshop (New Orleans, LA)
- 2022 **Keynote**, CVPR CVPM Workshop (New Orleans, LA)
- 2022 CMU Bioengineering Department Seminar (Pittsburgh, PA)
- 2022 Optical Sensors and Sensing Congress (Vancouver, CA)
- 2021 MIT AeroAstro Department (Cambridge, MA)
- 2021 Boston University Electrical Engineering Department (Boston, MA)
- 2021 EPFL, Lausanne Switzerland (Rescheduled COVID)
- 2021 UCLA School of Medicine Grand Rounds, Los Angeles CA (Los Angeles, CA)
- 2021 Snap Inc. (Virtual)
- 2021 Cornell AI in Medicine Seminar (Virtual)
- 2021 ETH Zurich Computer Vision Seminar (Zurich, Switzerland)
- 2021 Amazon + UCLA Science Hub Kickoff Event (Los Angeles, CA)
- 2021 Pixel Cafe at UCSD (Virtual)
- 2021 UC Berkeley Bioengineering, Guest Lecturer for Medical Device Design (Virtual)
- 2021 Black in Neuro Panel, Imperial College London (Virtual)
- 2021 Army Research Lab A2I2 Summit (Virtual)
- 2021 ICCV GigaVision Workshop (Virtual)
- 2021 CLEO Panel on AI and Photonics (Virtual)
- 2021 Army Research Lab Workshop on Synthetic Data (Virtual)
- 2020 SPIE Workshop on Computational Imaging (Virtual)
- 2020 Army Research Lab, Adelphi MD
- 2020 CVPR Visual Physics, Seattle WA
- 2019 DARPA/MEC workshop on AI, San Jose CA
- 2019 Stanford EE Department, Stanford CA
- 2019 MIT Media Lab, Cambridge MA
- 2019 Lemelson-MIT Eurekafest, Cambridge MA
- 2019 Computational Light Transport Summit, Banff Canada
- 2019 Indian Institute of Science, EE Department, Bangalore India
- 2019 Machine Learning Summer School, Bangalore India
- 2019 Honeywell Technology Symposium, Phoenix AZ
- 2019 Annual Research Review, UCLA, Los Angeles CA
- 2018 University of California, Los Angeles CA
- 2018 Carnegie Mellon University, Pittsburgh PA
- 2018 MIT CSAIL, Cambridge MA
- 2017 University of Tokyo, Tokyo JP
- 2017 Cymer Semiconductor Equipment, San Diego CA
- 2017 Computer Vision and Information Processing Society of Japan, Nagoya JP
- 2016 Honeywell Technology Symposium, Phoenix AZ
- 2016 Columbia CS, New York City, NY
- 2016 Cornell Tech, CS New York City, NY
- 2016 Mitsubishi Electric Research Lab (MERL), Boston MA

- 2016 University of Pennsylvania GRASP Lab, Philadelphia PA
- 2016 Princeton CS, Princeton, New Jersey
- 2016 Weizmann Institute of Science, Rehovat Israel
- 2016 Technion CS Department, Haifa Israel
- 2016 Mass General Hospital (MGH), Boston MA
- 2016 OSA Invited Talk, Heidelberg Germany
- 2016 Analog Devices, Cambridge MA
- 2015 Computational Imaging Summit, Daghstuhl Germany
- 2015 Microsoft Research, Redmond WA
- 2014 Qualcomm Research, San Diego CA
- 2014 Technion, Haifa Israel
- 2014 Microsoft iToF Workshop, Ein Gadi Israel
- 2014 IIT-Bombay, Bombay India
- 2013 Nokia Research, Bangalore India

Professional Service

Guest Editor, Applied Sciences, Special Issue on Computational Photography

Program chair, CVPR CCD 2021

Program chair, CVPR CCD 2020

Program chair, Industry relations, ICCP 2020

Program committee, Pacific Graphics 2019

Program committee, ICCP 2019

Program committee, CVPR 2019

Program committee, ICCP 2018

Program committee, CVPR 2018

Program committee, ICCP 2017

Program committee, CVPR 2017

Program committee, ICCV PBDL Workshop 2017

Program committee, CVPR 2016

Reviewer, SIGGRAPH

Reviewer, SIGGRAPH Asia

Reviewer, ICCV

Reviewer, CVPR

Reviewer, ECCV

Reviewer, ICCP

Reviewer, IEEE Trans Comp Imaging (TCI)

Reviewer, Various OSA journals

University Service, UCLA, MS admissions committee

University Service, UCLA, PhD thesis award committee

University Service, MIT, undergrad admissions committee

University Service, Lemelson-MIT student prize selection committee

IEEE, ACM, and OSA member

Textbook

TB.1 A. Bhandari, A. Kadambi, R. Raskar, Computational Imaging (450 pages). MIT Press, 2022 (E-PDF at imagingtext.github.io)

Papers

- P.26 P. Chari, Y. Ba, S. Athreya, and A. Kadambi. MIME: Minority Inclusion for Majority Group Enhancement of AI Performance. ECCV 2022
- Y. Ba, H. Zhang, E. Yang, A. Suzuki, A. Pfahnl, C. Chandrappa, C. De Melo, S. You,
 S. Soatto, A. Wong, and A. Kadambi. Not Just Streaks: Towards Ground Truth for Single Image Deraining. ECCV 2022
- P.24 Y. Ba*, Z. Wang*, D. Karinca, O. Bozkurt, and A. Kadambi. Style Transfer with Bio-realistic Appearance Manipulation for Skin-tone Inclusive Plethysmography ICCP 2022
- P.23 A. Vilesov*, P. Chari*, A. Armouti*, A. B. Harish, K. Kulkarni, A. Deoghare, L. Jalilian, and A. Kadambi. *Blending Camera and 77 GHz Radar Sensing for Equitable, Robust Plethysmography.* SIGGRAPH 2022
- P.22 Z. Wang, Y. Ba, P. Chari, O. Bozkurt, G. Brown, P. Patwa, N. Vaddi, L. Jalilian, and A. Kadambi, Synthetic *Generation of Face Videos with Plethysmograph Physiology*. CVPR 2022
- P.21 S. Pei, P. Chari, X. Wang, X. Yang, **A. Kadambi**, and Y. Zhang. *ForceSight: Non-Contact Force Sensing with Laser Speckle Imaging*. **UIST** 2022
- P.20 A. Kadambi, Achieving Fairness in Medical Devices. Science 2021 no. 372.6537
- P.19 A. Kalra, B. Brown, G Stoppi, R. Agrawal, and A. Kadambi. *Towards Rotation Invariance in Object Detection*. ICCV 2021.
- P.18 **A. Kadambi** and A. Madni, *Artificial Intelligence: From Ancient Greeks to Self-Driving Cars and Beyond*, **Nat'l Academy of Engineering Bridge** 2021
- P.17 Y. Ba, A. Gilbert, F. Wang, J. Yang, R. Chen, Y. Wang, B. Shi and **A. Kadambi.** *Deep Shape from Polarization.* **ECCV** 2020.
- P.16 K. Tanaka, Y. Mukaigawa, and **A. Kadambi.** *Polarized Non-line-of-sight Imaging*. **CVPR** 2020
- P.15 A. Kalra, V. Taamazyan, S. Rao, K. Venkataraman, R Raskar, and A. Kadambi.

 Deep Polarization Cues for Transparent Object Segmentation. CVPR 2020 (Top 3% paper)

- P.14 P. Chari, C. Talegaonkar, Y. Ba, and **A. Kadambi**. *Visual Physics: Discovering Physical Laws from Video*. arXiv:1911.11893, 2019
- P.13 Y. Ba, G. Zhao, and **A. Kadambi**. *Blending Diverse Physical Priors with Neural Networks*. arXiv:1910.00201, 2019
- P.12 K. Tanaka, N. Ikeya, T. Takatani, H. Kubo, T. Funatomi, V. Ravi, **A. Kadambi**, and Y. Mukaigawa. *Time-resolved Far Infrared Light Transport Decomposition for Thermal Photometric Stereo*. IEEE Transactions on Pattern Analysis and Machine Intelligence (**TPAMI**), 2020
- P.11 T. Maeda, Y. Wang, R. Raskar, and A. Kadambi. *Thermal Non-line-of-sight Imaging*. IEEE ICCP 2019
- P.10 T. Maeda, A. Kadambi, Y. Schechner, and R. Raskar. *Dynamic heterodyne interferometry*. IEEE ICCP 2018 (Best Paper Award)
- P.9 **A. Kadambi** and R. Raskar. *Rethinking Machine Vision Time of Flight with GHz Heterodyning*. IEEE **Access** 2017
- P.8 **A. Kadambi**, V. Taamazyan, B. Shi, and R. Raskar. *Depth sensing using geometrically constrained polarization normals*. In **IJCV** 2017 (**Best Papers Issue**)
- P.7 **A. Kadambi**, J. Schiel, and R. Raskar. *Macroscopic Interferometry: Rethinking Depth Estimation with Frequency-Domain Time of Flight*. IEEE **CVPR** 2016 **(Oral, 3% acceptance rate).**
- P.6 **A. Kadambi**, H. Zhao, B. Shi, and R. Raskar. *Occluded Imaging with Time of Flight Sensors*. In ACM Transactions on Graphics (pres **SIGGRAPH** 2016)
- P.5 **A. Kadambi,** V. Taamazyan, B. Shi, and R. Raskar. *Polarized 3D: enhanced 3D sensing fusing depth and polarization cues.* **ICCV** 2015 (**Oral, 3% acceptance rate**)
- P.4 N. Naik, **A. Kadambi**, C. Rhemann, S. Izadi, R. Raskar and S. Kang. *A light transport model for mitigating multipath interference in ToF sensors*. In **CVPR** 2015.
- P.3 A. Bhandari, A. Kadambi, R. Whyte, C. Barsi, M. Feigin, A. Dorrington, and R. Raskar. Resolving multi-path interference in time-of-flight imaging via modulation frequency diversity and sparse regularization. Optics Letters, 2014
- P.2 **A. Kadambi**, A. Bhandari, R. Whyte, A. Dorrington and R. Raskar. *Demultiplexing Illumination via low-cost sensing and nanosecond coding.* **ICCP** 2014.
- P.1 **A. Kadambi**, R. Whyte, A. Bhandari, L. Streeter, C. Barsi, A. Dorrington, and R. Raskar. *Coded time of flight cameras: sparse deconvolution to address multipath*

interference and recover time profiles. ACM Transactions on Graphics (pres **SIGGRAPH Asia** 2013).

Patents

US.19	Systems and methods for transparent object segmentation using polarization cues. US Patent 11,302,012
US.18	Systems and methods for pose detection and measurement US Patent 11,295,475
US.17	Systems and methods for camera exposure control. US Patent 11,290,658
US.16	Systems and methods for surface modeling using polarization cues. US Patent 11,270,110
US.15	Systems and methods for characterizing object pose detection and measurement systems. US Patent 11,195,303
US.14	Methods and apparatus for gigahertz time-of-flight imaging. US Patent 11,181,623
US.13	Depth maps with polarization cues. US Patent 10,557,705
US.12	X-ray imaging from temporal measurements. US Patent 10,527,562
US.11	Time-of-flight sensor. US Patent 10,488,520
US.10	Fluorescent lifetime with periodically modulated light. US Patent 10,337,993
US.9	Depth maps with polarization cues. US Patent 10,260,866
US.8	Methods and apparatus for time-of-flight imaging. US Patent 10,191,154
US.7	Fluorescence lifetime imaging with pulsed light. US Patent 10,190,983
US.6	Methods and apparatus for virtual sensor array. US Patent 9,897,699
US.5	Intensity-based depth sensing system and method. US Patent 9,897,698
US.4	Methods and apparatus for coded time-of-flight camera. US Patent 9,778,363
US.3	Depth sensing using optical pulses and fixed coded aperture. US Patent 9,638,801
US.2	Methods and apparatus for demultiplexing illumination. US Patent 9,451,141
US.1	Methods and apparatus for multi-frequency camera. US Patent 9,405,008